

M/A-COM Technology Solutions Inc.
100 Chelmsford Street
Lowell, Massachusetts 01851
www.macomtech.com



20 February 2014

Customer Name
Customer Address
Customer Address
ATTN: Quality/Purchasing Manager

Subject: Product Change Notification- MASW-011036 Bond Pad Stack-up

PCN #: PCN-00603

Dear Valued Customer:

As part of MACOM's continuous improvement program, this communication is to inform you that a minor change to the part number listed below has been made, effective immediately.

The bond pad stack up is being changed from Ti-Pt-Au-Ti-Pt-Au to AuGe-Ni-Au-Ti-Pt-Au-Ti-Pt-Au.

This minor change is being made to increase the latitude of bonding parameters that the die can withstand.

There are no changes in form, fit, function, or reliability.

MASW-011036

If there are any questions about this communication, please contact your local M/A-COM sales representative.

Sincerely,

Loren Reifsteck
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